



BSI Standards Publication

Attachment materials for electronic assembly

Part 1-3: Requirements for electronic grade solder alloys and fluxed and non-fluxed solid solder for electronic soldering applications (IEC 61190-1-3:2017)

National foreword

This British Standard is the UK implementation of EN IEC 61190-1-3:2018. It is identical to IEC 61190-1-3:2017. It supersedes BS EN 61190-1-3:2007+A1:2010, which is withdrawn.

The UK participation in its preparation was entrusted to Technical Committee EPL/501, Electronic Assembly Technology.

A list of organizations represented on this committee can be obtained on request to its secretary.

This publication does not purport to include all the necessary provisions of a contract. Users are responsible for its correct application.

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Amendments/corrigenda issued since publication

Date	Text affected
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